

SWITCHING REGULATOR CONTROL CIRCUIT

<R> DESCRIPTION

The μ PC494 is a PWM type switching regulator control circuit.

Included in this device are a 5 V voltage reference, dual error amplifiers, a variable frequency sawtooth-wave generating oscillator, a comparator for dead-time control, a flip flop, dual alternating output switches, and a buffer to output source and sink currents.

Error amplifiers have wide common mode input voltage capability, and circuits for voltage feedback and over current protection are easy to configure. The μ PC494 can be applied to all types of switching regulators, including chopper type regulators.

<R> FEATURES

- 250 mA output buffer to output sink and source currents
- Switchable operation mode between a single-end mode and a push-pull mode
- No double pulsing during transient condition
- Adjustable dead-time (0 to 100%)
- Internal 5 V output voltage reference circuit
- Error amplifiers with phase-compensating function
- Providing master-slave operation (synchronizing multiple ICs)
- With malfunction prevention circuit for low level supply voltage
- Package variations available for different applications

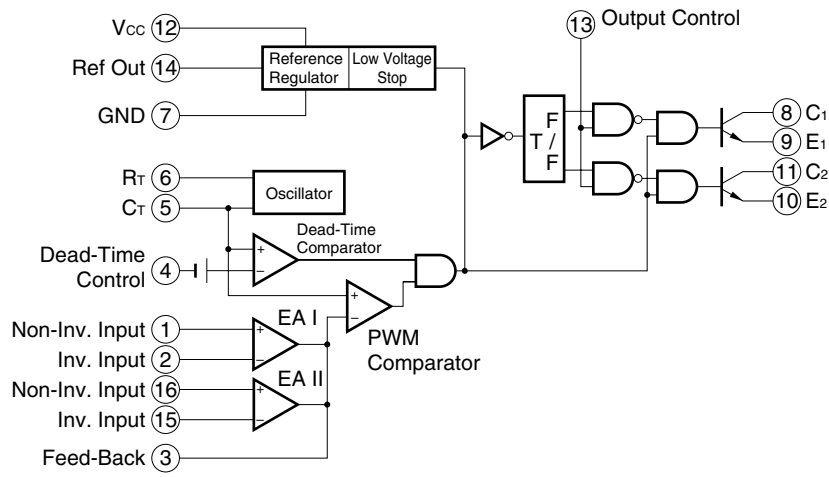
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Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.

<R> ORDERING INFORMATION

Part Number	Package	Package Type
μPC494C	16-pin plastic DIP (7.62 mm (300))	<ul style="list-style-type: none"> • plastic magazine
μPC494GS	16-pin plastic SOP (7.62 mm (300))	<ul style="list-style-type: none"> • plastic magazine
μPC494GS-E1	16-pin plastic SOP (7.62 mm (300))	<ul style="list-style-type: none"> • embossed taping • Pin 1 on draw-out side • 2500 pcs/reel
μPC494GS-E2	16-pin plastic SOP (7.62 mm (300))	<ul style="list-style-type: none"> • embossed taping • Pin 1 at take-up side • 2500 pcs/reel
μPC494GT-A ^{Note}	16-pin plastic SOP (9.53 mm (375))	<ul style="list-style-type: none"> • plastic magazine
μPC494GT-E1-A ^{Note}	16-pin plastic SOP (9.53 mm (375))	<ul style="list-style-type: none"> • embossed taping • Pin 1 on draw-out side • 1500 pcs/reel
μPC494GT-E2-A ^{Note}	16-pin plastic SOP (9.53 mm (375))	<ul style="list-style-type: none"> • embossed taping • Pin 1 at take-up side • 1500 pcs/reel
μPC494GS-A ^{Note}	16-pin plastic SOP (7.62 mm (300))	<ul style="list-style-type: none"> • plastic magazine
μPC494GS-E1-A ^{Note}	16-pin plastic SOP (7.62 mm (300))	<ul style="list-style-type: none"> • embossed taping • Pin 1 on draw-out side • 2500 pcs/reel
μPC494GS-E2-A ^{Note}	16-pin plastic SOP (7.62 mm (300))	<ul style="list-style-type: none"> • embossed taping • Pin 1 at take-up side • 2500 pcs/reel

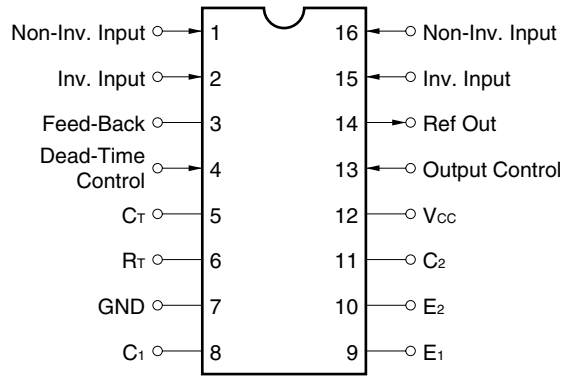
Note Pb-free (This product does not contain Pb in the external electrode and other parts.)

BLOCK DIAGRAM



PIN CONFIGURATION (Top View)

<R> • μ PC494C, 494GS, 494GT-A, 494GS-A



<R> **ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise noted)**

Characteristics	Symbol	μPC494C	μPC494GS	μPC494GT-A	μPC494GS-A	Unit
Supply Voltage	V _{CC}	-0.3 to +41				V
Error Amplifier Input Voltage	V _{ICM}	-0.3 to V _{CC} +0.3				V
Dead-time Comparator Input Voltage	V _{DTC}	-0.3 to +5.25				V
Output Voltage	V _{CER}	-0.3 to +41				V
Output Current	I _C	250				mA
Total Power Dissipation	P _T	1000	650 ^{Note}	780 ^{Note}	650 ^{Note}	mW
Operating Ambient Temperature	T _A	-20 to +85				°C
Storage Temperature	T _{stg}	-65 to +150				°C

Note With 5 cm x 5 cm x 1.6 mmt glass-epoxy substrate.

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

RECOMMENDED OPERATING CONDITIONS

Characteristics	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	V _{CC}	7		40	V
Output Voltage	V _{CER}	-0.3		+40	V
<R> Output Current (per output stage)	I _C			200	mA
Error Amplifier Sink Current	I _{OAMP}			-0.3	mA
Timing Capacitor	C _T	0.47		10000	nF
Timing Resistance	R _T	1.8		500	kΩ
Oscillation Frequency	f _{OSC}	1		300	kHz
Operating Ambient Temperature	T _A	-20		+70	°C

Caution The recommended operating range may be exceeded without causing any problems provided that the absolute maximum ratings are not exceeded. However, if the device is operated in a way that exceeds the recommended operating conditions, the margin between the actual conditions of use and the absolute maximum ratings is small, and therefore thorough evaluation is necessary. The recommended operating conditions do not imply that the device can be used with all values at their maximum values.

ELECTRICAL SPECIFICATIONS (V_{CC} = 15 V, f = 10 kHz, -20°C ≤ T_A ≤ +70°C, unless otherwise noted)

(1/2)

Block	Characteristics		Symbol	Conditions	MIN.	TYP. ^{Note1}	MAX.	Unit
Reference Section	Output Voltage		V _{REF}	I _{REF} = 1 mA, T _A = 25°C	4.75	5	5.25	V
	Line Regulation		REG _{IN}	7 V ≤ V _{CC} ≤ 40 V, I _{REF} = 1 mA, T _A = 25°C		8	25	mV
	Load Regulation		REG _L	1 mA ≤ I _{REF} ≤ 10 mA, T _A = 25°C		1	15	mV
	Temperature Coefficient		ΔV _{REF} / ΔT	-20°C ≤ T _A ≤ +85°C, I _{REF} = 1 mA		0.01	0.03	%/°C
	Short Circuit Output Current ^{Note2}		I _{SHORT}	V _{REF} = 0 V		50		mA
Oscillator Section	Frequency		f _{OSC}	C _T = 0.01 μF, R _T = 12 kΩ		10		kHz
	Standard Deviation of Frequency ^{Note3}			7 V ≤ V _{CC} ≤ 40 V, T _A = 25°C, under recommended operating conditions of C _T and R _T constants.		10		%
	Frequency Change with Voltage			7 V ≤ V _{CC} ≤ 40 V, T _A = 25°C, C _T = 0.01 μF, R _T = 12 kΩ		1		%
	Frequency Change with Temperature			0°C ≤ T _A ≤ 70°C, C _T = 0.01 μF, R _T = 12 kΩ		1	2	%
Dead- Time Control Section	Input Bias Current			0 V ≤ V _{DTC} ≤ 5.25 V		-2	-10	μA
	Maximum Duty Cycle (Each Output)			V _{DTC} = 0 V	45	49		%
	Input Threshold Voltage 1		V _{TH1}	Output pulse 0% duty cycle		3	3.3	V
	Input Threshold Voltage 2		V _{TH2}	Output pulse maximum duty cycle	0			V
Error Amplifier 1, 2 Section	Input Offset Voltage		V _{IO}	V _{OAMP} = 2.5 V		2	10	mV
	Input Offset Current		I _{IO}	V _{OAMP} = 2.5 V		25	250	nA
	Input Bias Current			V _{OAMP} = 2.5 V		0.2	1	μA
	Common Mode Input Voltage	Low level	V _{ICM}	7 V ≤ V _{CC} ≤ 40 V	-0.3			V
		High level			V _{CC} - 2			
	Open Loop Voltage Gain		A _V	V _{OAMP} = 0.5 to 3.5 V, T _A = 25°C	60	80		dB
	Unity Gain Bandwidth			T _A = 25°C	500	830		kHz
	Common Mode Rejection Ratio		CMR	V _{CC} = 40 V, T _A = 25°C	65	80		dB
	Output Sink Current			V _{OAMP} = 0.7 V	0.3	0.7		mA
Output Source Current			V _{OAMP} = 3.5 V	-2	-10		mA	
PWM Section	Input Threshold Voltage (Pin 3)			Output pulse 0% duty cycle, see Figure 1.		4	4.5	V
	Input Sink Current			V _(Pin 3) = 0.7 V	0.3	0.7		mA

Notes 1. The TYP. values are values at T_A = 25°C, except for the characteristics of temperature.

2. The short circuit output current flow must be terminated within 1 second.

Repeated operations are allowed while internal heat accumulation is within a safe range.

3. Standard deviation is a measure of the statistical distribution about the mean as derived from the formula;

$$\sigma = \sqrt{\frac{\sum_{n=1}^N (X_n - \bar{X})^2}{N - 1}}$$

Calculation expression of frequency f_{osc} is as follows ;

$$f_{osc} \cong \frac{1}{0.817 R_T \bullet C_T + 1.42 \bullet 10^{-6}} \text{ (Hz)} \quad [R_T] = \Omega, [C_T] = F$$

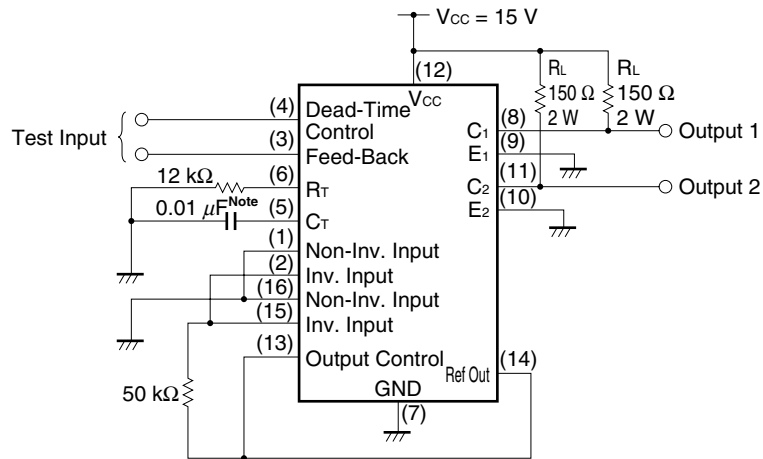
(2/2)

Block	Characteristics	Symbol	Conditions	MIN.	TYP. ^{Note}	MAX.	Unit	
Output Section	Collector Cut-off Current	I_{CER}	$V_{CE} = 40\text{ V}, V_{CC} = 40\text{ V},$ Common Emitter			100	μA	
	Emitter Cut-off Current		$V_{CC} = V_C = 40\text{ V}, V_E = 0\text{ V},$ Emitter Follower			-100	μA	
	Collector Saturation Voltage	Common Emitter	$V_{CE(sat)}$	$I_C = 200\text{ mA}, V_E = 0\text{ V}$		0.95	1.3	V
		Emitter Follower	$V_{CE(ON)}$	$I_E = -200\text{ mA}, V_C = 15\text{ V}$		1.6	2.5	V
	Output Voltage Rise Time	Common Emitter	t_{r1}	$V_{CC} = 15\text{ V}, R_L = 150\ \Omega,$ $I_C \cong 100\text{ mA}, T_A = 25^\circ\text{C},$ see Figure 1 .		100	200	ns
	Output Voltage Fall Time		t_{f1}			70	200	ns
	Output Voltage Rise Time	Emitter Follower	t_{r2}	$V_C = 15\text{ V}, R_L = 150\ \Omega,$ $I_E \cong 100\text{ mA}, T_A = 25^\circ\text{C},$ see Figure 1 .		100	200	ns
	Output Voltage Fall Time		t_{f2}			70	200	ns
Total Device	Standby Current	$I_{CC(S.B)}$	$V_{CC} = 15\text{ V},$ all other pins open.		8	12.5	mA	
	Bias Current	$I_{CC(BI)}$	$V_{(Pin\ 4)} = 2\text{ V},$ see Figure 1 .		10		mA	

Note The TYP. values are values at $T_A = 25^\circ\text{C}$, except for the characteristics of temperature.

TEST CIRCUIT AND WAVEFORM CHARACTERISTICS

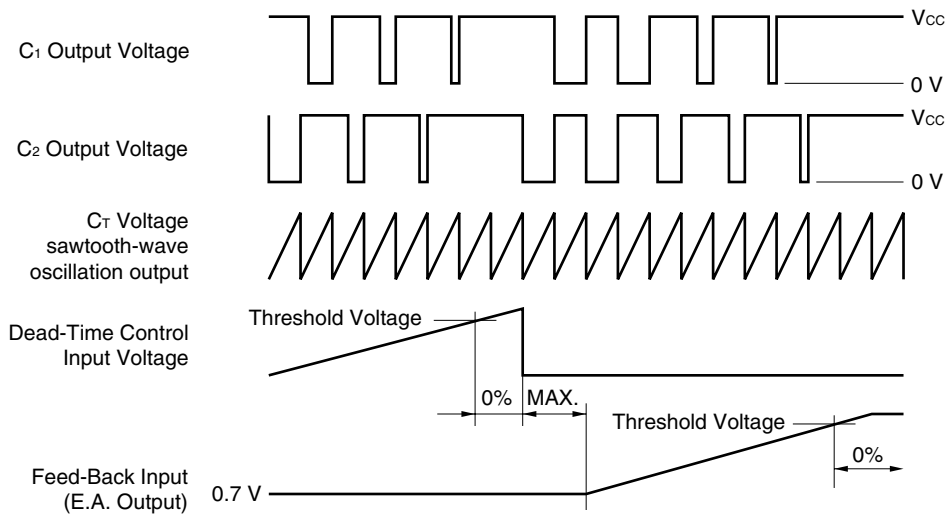
Figure1. Test Circuit



Note Recommend film capacitor.

Caution When the emitter follower is output, connect C₁ and C₂ to V_{cc} and E₁ and E₂ to GND via R_L.

Figure2. Voltage Waveform



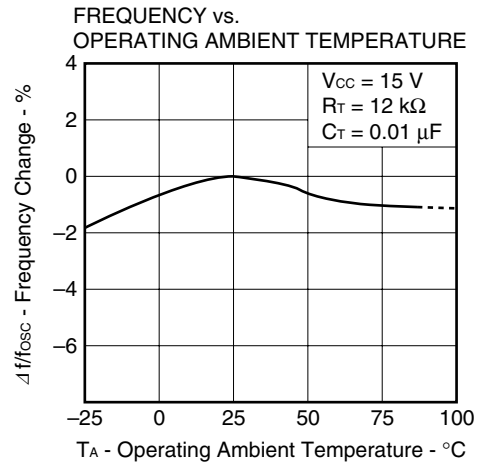
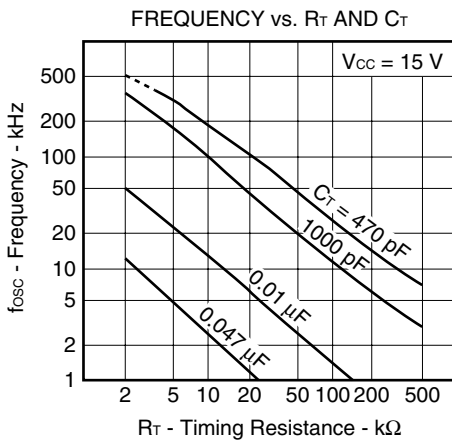
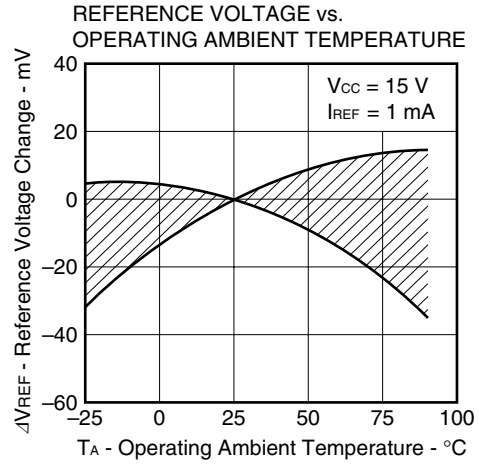
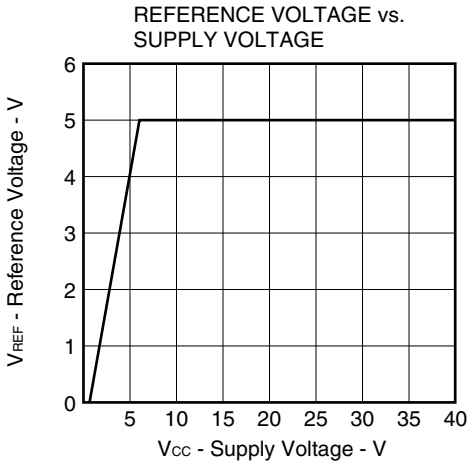
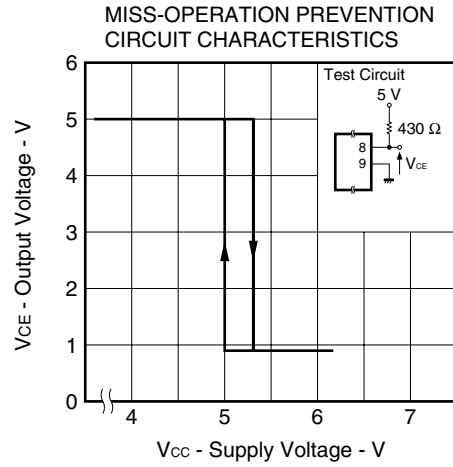
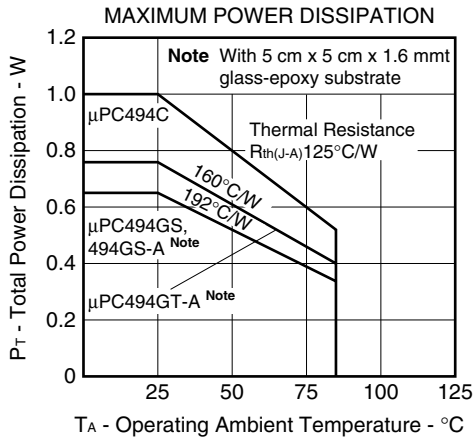
Connection of Output Control Pin (Pin 13)

Output Control Input (Pin 13)	Operation Mode
Ref Out	push-pull
GND	Single-ended operation (common-mode output of C ₁ , C ₂)

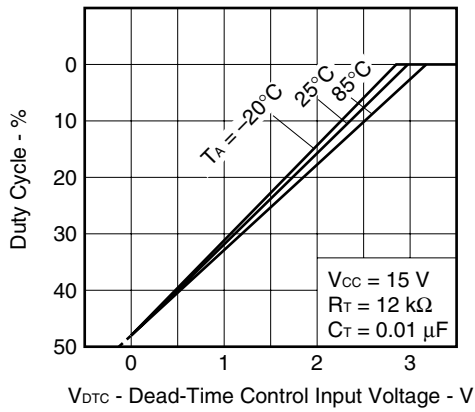
TYPICAL PERFORMANCE CHARACTERISTICS

(Unless otherwise specified, $T_A = 25^\circ\text{C}$, $V_{CC} = 15\text{ V}$, Reference)

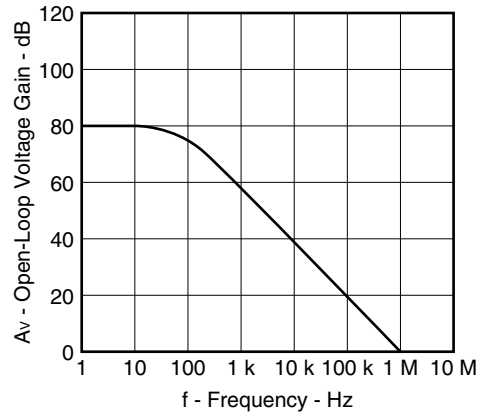
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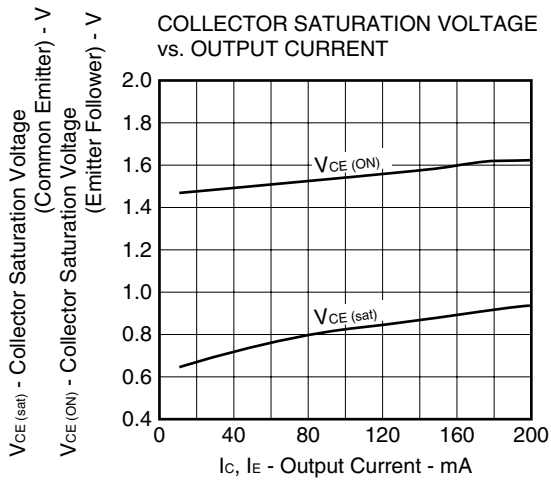
DUTY CYCLE vs. DEAD-TIME CONTROL INPUT VOLTAGE



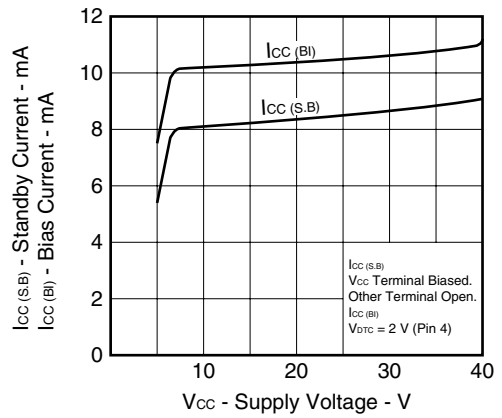
OPEN-LOOP VOLTAGE GAIN vs. FREQUENCY



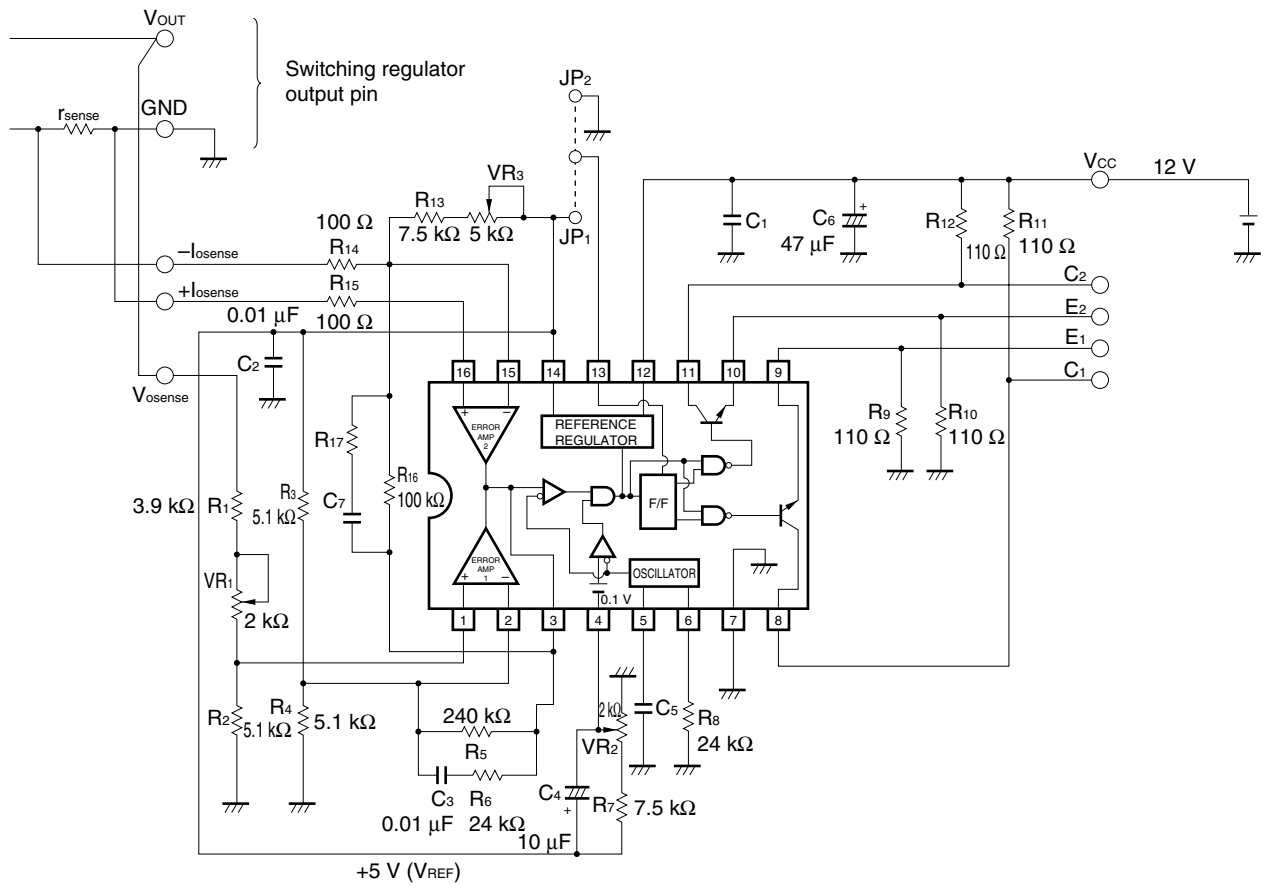
COLLECTOR SATURATION VOLTAGE vs. OUTPUT CURRENT



STANDBY AND BIAS CURRENT vs. SUPPLY VOLTAGE

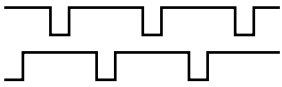
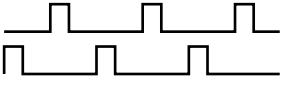




BASIC APPLICATION CIRCUIT



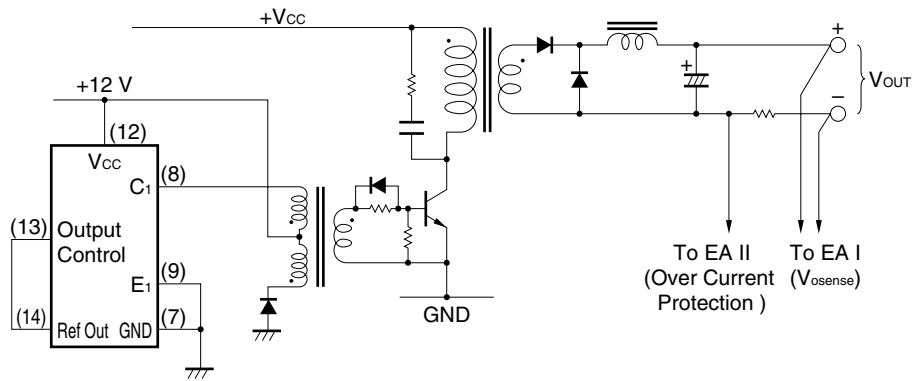
Remark $f_{osc} \cong 40$ kHz, C₅ = 1000 pF (Recommend film capacitor)

CONNECTION DIAGRAM

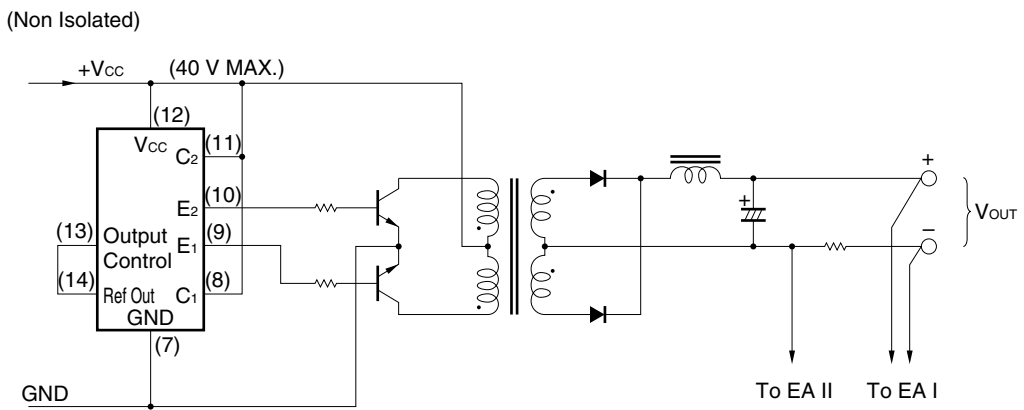
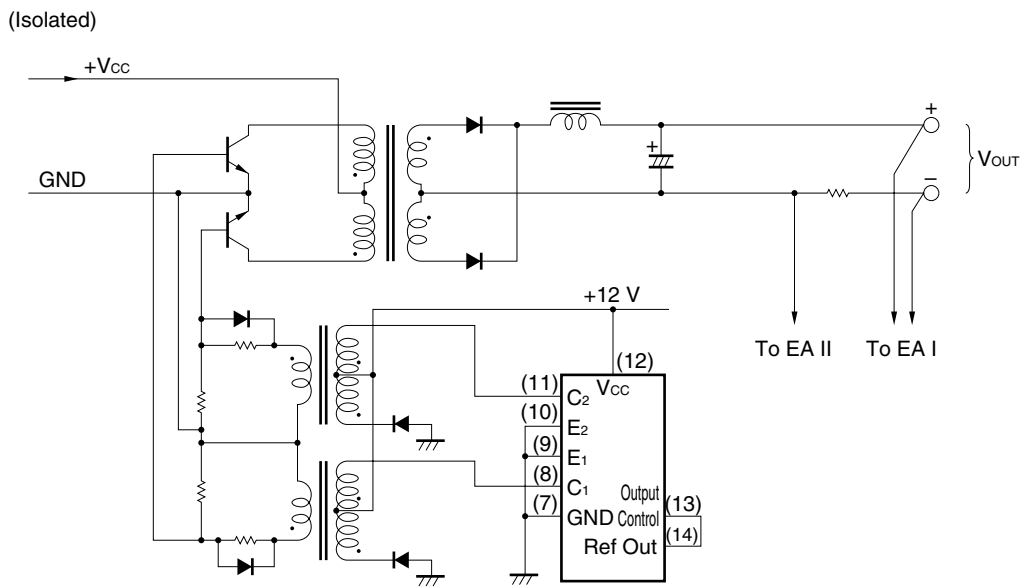
Operation Mode	Output Control Input (Pin 13)	Output Mode	Output Voltage Waveform
Push-pull	Ref Out (Pin 14) (JP1 Wired)	Sink (R ₉ , R ₁₀ short)	C ₁ C ₂ 
		Source (R ₁₁ , R ₁₂ short)	E ₁ E ₂ 
Single-ended operation	GND (Pin 7) (JP2 Wired)	Sink (R ₉ , R ₁₀ short)	C ₁ , C ₂ 
		Source (R ₁₁ , R ₁₂ short)	E ₁ , E ₂ 

TYPICAL EXAMPLE OF APPLICATION CIRCUITS

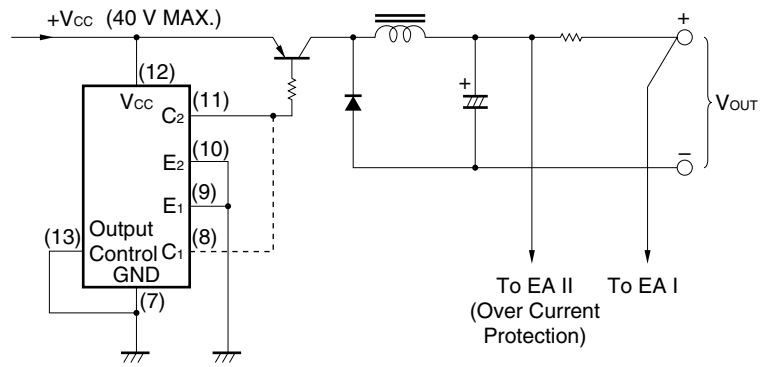
1) Forward Type



2) Push-pull Type



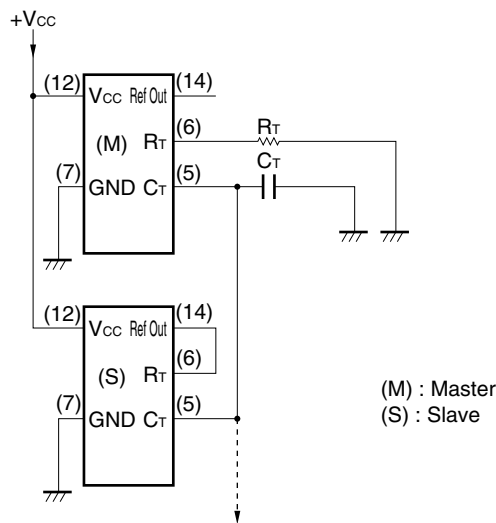
3) Step-down Chopper



Remark The dotted line indicates the connection in case of large current.

EXAMPLE OF MASTER-SLAVE CONNECTION

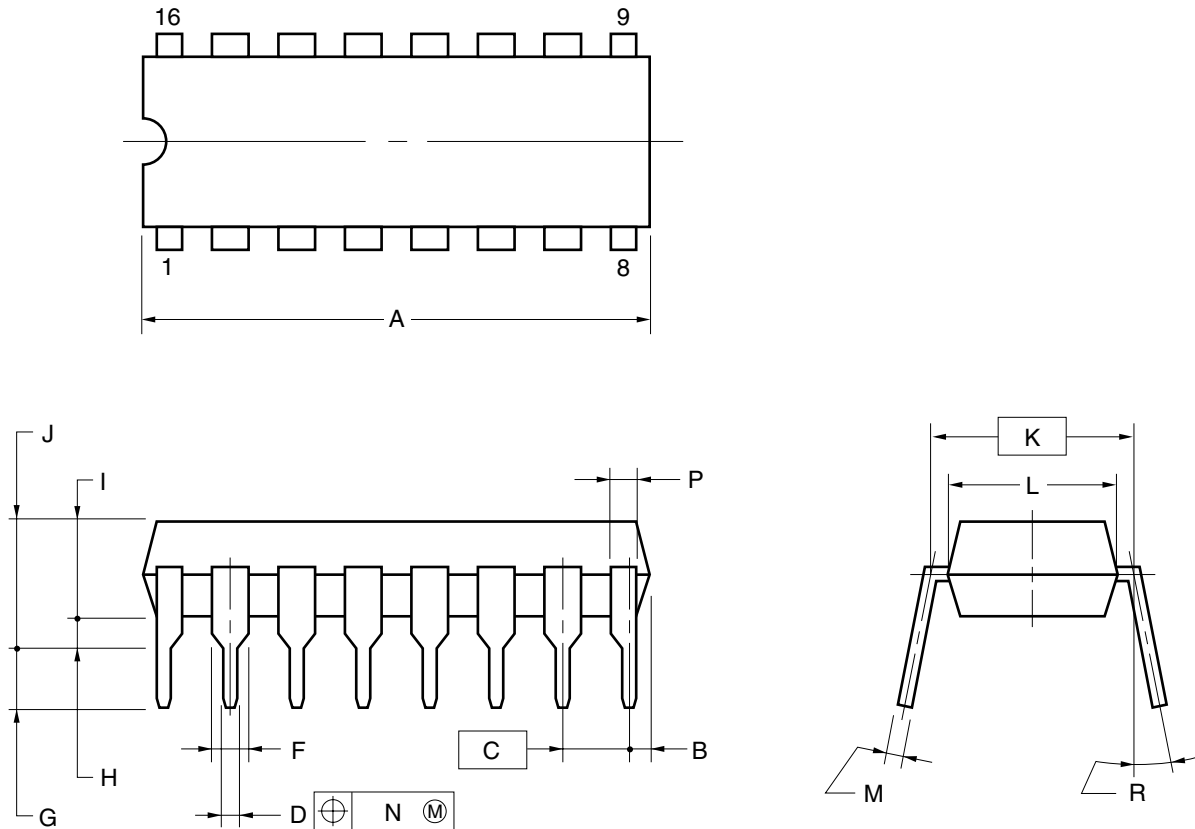
To synchronize μPC494 ICs, connect the pin 6 (R_T) of a slave IC to pin 14 (Ref Out) of the same IC, and connect both C_T pins of master and slave ICs after confirming oscillator of slave IC is stopped.



PACKAGE DRAWINGS (Unit : mm)

μPC494C

16-PIN PLASTIC DIP (7.62mm(300))



NOTES

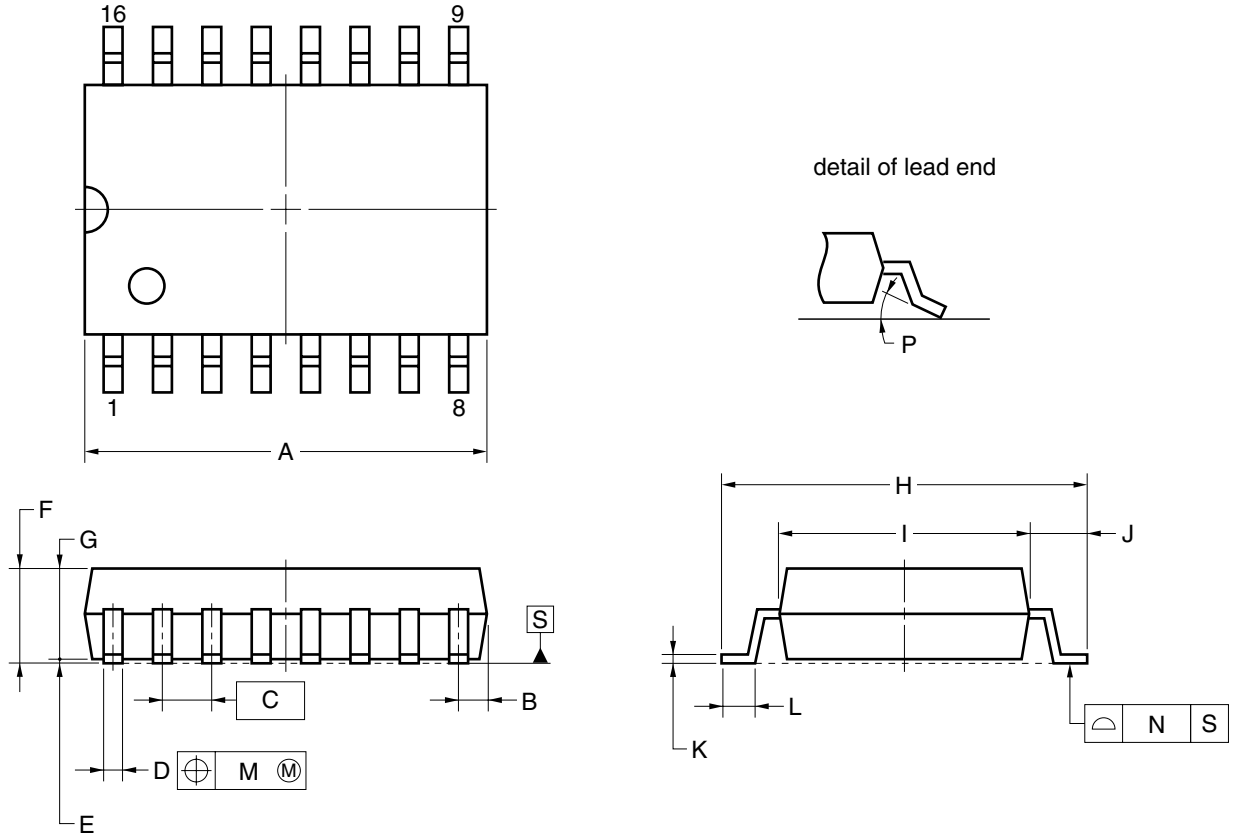
1. Each lead centerline is located within 0.25 mm of its true position (T.P.) at maximum material condition.
2. Item "K" to center of leads when formed parallel.

ITEM	MILLIMETERS
A	20.32 MAX.
B	1.27 MAX.
C	2.54 (T.P.)
D	0.50±0.10
F	1.1 MIN.
G	3.5±0.3
H	0.51 MIN.
I	4.31 MAX.
J	5.08 MAX.
K	7.62 (T.P.)
L	6.5
M	0.25 ^{+0.10} _{-0.05}
N	0.25
P	1.1 MIN.
R	0~15°

P16C-100-300B-2

<R> μPC494GT-A

16-PIN PLASTIC SOP (9.53 mm (375))



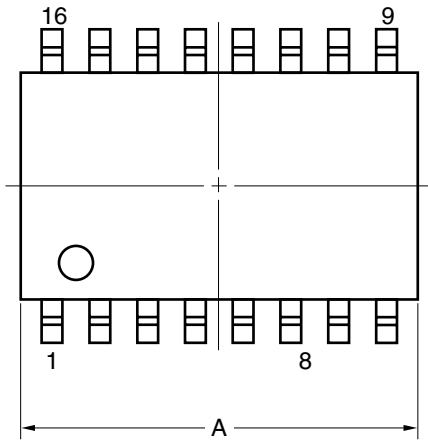
NOTE
 Each lead centerline is located within 0.12 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
A	10.2±0.26
B	0.805 MAX.
C	1.27 (T.P.)
D	0.42 ^{+0.08} _{-0.07}
E	0.125±0.075
F	2.9 MAX.
G	2.50±0.2
H	10.3±0.3
I	7.2±0.2
J	1.6±0.2
K	0.17 ^{+0.08} _{-0.07}
L	0.8±0.2
M	0.12
N	0.10
P	3° ^{+7°} _{-3°}

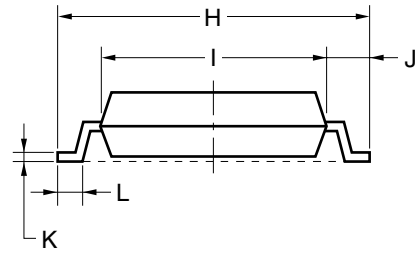
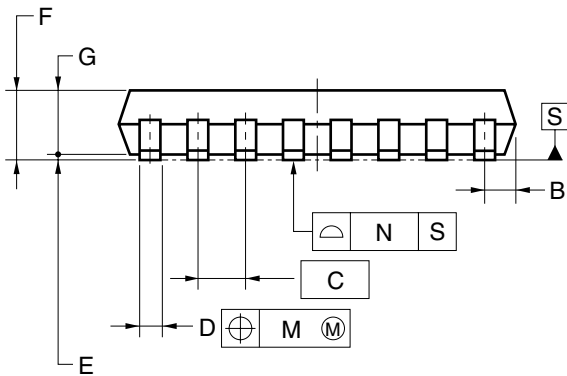
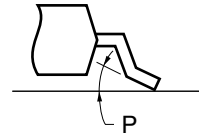
P16GT-50-375B-2

μPC494GS, 494GS-A

16-PIN PLASTIC SOP (7.62 mm (300))



detail of lead end



NOTE

Each lead centerline is located within 0.12 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
A	10.2±0.2
B	0.78 MAX.
C	1.27 (T.P.)
D	0.42 ^{+0.08} _{-0.07}
E	0.1±0.1
F	1.65±0.15
G	1.55
H	7.7±0.3
I	5.6±0.2
J	1.1±0.2
K	0.22 ^{+0.08} _{-0.07}
L	0.6±0.2
M	0.12
N	0.10
P	3° ^{+7°} _{-3°}

P16GM-50-300B-6

<R> **RECOMMENDED SOLDERING CONDITIONS**

The μPC494 should be soldered and mounted under the following recommended conditions.

For soldering methods and conditions other than those recommended below, contact an NEC Electronics sales representative.

For technical information, see the following website.

Semiconductor Device Mount Manual (<http://www.necel.com/pkg/en/mount/index.html>)

Type of Through-hole Device

μPC494C: 16-pin plastic DIP (7.62 mm (300))

Process	Conditions	Symbol
Wave Soldering (only to leads)	Solder temperature: 260°C or below, Flow time: 10 seconds or less	WS60-00
Partial Heating Method	Pin temperature: 300°C or below, Heat time: 3 seconds or less (Per each side of the device)	P300

Caution For through-hole device, the wave soldering process must be applied only to leads, and make sure that the package body does not get jet soldered.

Type of Surface Mount Device

μPC494GS: 16-pin plastic SOP (7.62 mm (300))

Process	Conditions	Symbol
Infrared Ray Reflow	Maximum temperature (package's surface temperature): 235°C or below, Time at maximum temperature: 10 seconds or less, Time at temperature higher than 210°C: 30 seconds or less, Preheating time at 100 to 160°C: 30 to 60 seconds, Times: 3 times, Flux: Rosin flux with low chlorine (0.2 Wt% or below) recommended.	IR35-00-3
Vapor Phase Soldering	Maximum temperature (package's surface temperature): 215°C or below, Reflow time: 25 to 40 seconds or less (at 200°C or higher), Preheating time at 120 to 150°C: 30 to 60 seconds, Times: 3 times, Flux: Rosin flux with low chlorine (0.2 Wt% or below) recommended.	VP15-00-3
Wave Soldering	Solder temperature: 260°C or below, Flow time: 10 seconds or less, Maximum number of flow processes: 1 time, Preheating temperature: 120°C MAX. (Package surface temperature).	WS60-00-1
Partial Heating Method	Pin temperature: 350°C or below, Heat time: 3 seconds or less (Per each side of the device), Flux: Rosin flux with low chlorine (0.2 Wt% or below) recommended.	P350

Caution Apply only one kind of soldering condition to a device, except for "partial heating method", or the device will be damaged by heat stress.

μPC494GT-A^{Note1}: 16-pin plastic SOP (9.53 mm (375))

Process	Conditions	Symbol
Infrared Ray Reflow	Maximum temperature (package's surface temperature): 260°C or below, Time at maximum temperature: 10 seconds or less, Time at temperature higher than 220°C: 60 seconds or less, Preheating time at 160 to 180°C: 60 to 120 seconds, Times: 3 times, Exposure limit: 7 days ^{Note2} (after that, prebake at 125°C for 20 hours), Flux: Rosin flux with low chlorine (0.2 Wt% or below) recommended.	IR60-207-3
Wave Soldering	Solder temperature: 260°C or below, Flow time: 10 seconds or less, Maximum number of flow processes: 1 time, Preheating temperature: 120°C MAX. (Package surface temperature), Exposure limit: 7 days ^{Note2} (after that, prebake at 125°C for 20 hours).	WS60-207-1
Partial Heating Method	Pin temperature: 350°C or below, Heat time: 3 seconds or less (Per each side of the device), Flux: Rosin flux with low chlorine (0.2 Wt% or below) recommended.	P350

Notes 1. Pb-free (This product does not contain Pb in the external electrode and other parts.)

2. After opening the dry pack, store it a 25°C or less and 65% RH or less for the allowable storage period.

μPC494GS-A^{Note}: 16-pin plastic SOP (7.62 mm (300))

Process	Conditions	Symbol
Infrared Ray Reflow	Maximum temperature (package's surface temperature): 260°C or below, Time at maximum temperature: 10 seconds or less, Time at temperature higher than 220°C: 60 seconds or less, Preheating time at 160 to 180°C: 60 to 120 seconds, Times: 3 times, Flux: Rosin flux with low chlorine (0.2 Wt% or below) recommended.	IR60-00-3
Wave Soldering	Solder temperature: 260°C or below, Flow time: 10 seconds or less, Maximum number of flow processes: 1 time, Preheating temperature: 120°C MAX. (Package surface temperature).	WS60-00-1
Partial Heating Method	Pin temperature: 350°C or below, Heat time: 3 seconds or less (Per each side of the device), Flux: Rosin flux with low chlorine (0.2 Wt% or below) recommended.	P350

Note Pb-free (This product does not contain Pb in the external electrode and other parts.)

Caution Apply only one kind of soldering condition to a device, except for "partial heating method", or the device will be damaged by heat stress.

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